	٦	μ_	Document ID	Issue Date	Pages	Title	Current OR
			US 6278264 B1	20010821	18	Flip-chip switching regulator 323/282	323/282
57	⊠		US 6206705 B1	20010327	ω	Three-dimensional modular electronic interconnection system	439/69
	☒		US 5787174 A	19980728	10	Remote identification of integrated circuit	713/189
			US 5779839 A	19980714	23	Method of manufacturing an enclosed transceiver	156/213
	☒		US 5724728 A	19980310	7	Method of mounting an integrated circuit to a mounting surface	29/840
			US 5451715 A	19950919	σ	Molded package integrated circuit with electrochemical cell	174/52.4

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257/678	257/678; 439/73	156/308.4; 29/855	380/270; 438/19; 713/168	324/764; 342/44:	257/704; 361/726; 439/66; 439/74	257/700	Current XRef
							Retrieval Classif
Hundt, Michael J. et al.	Bond, Robert H. et al.	Tuttle, Mark E. et al.	Tuttle, John R.		Bolotin, Gary S. et al	Burstein, Andrew J. et al.	Inventor
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